

Proforma

Companies open to your department

Company : Taiwan Semiconductor Manufacturing Company
Company Name : Taiwan Semiconductor Manufacturing Company
Nature Of Business : Semiconductor
Designation : Chip Design Engineer
Tentative Job Location : Hsinchu City, Taiwan

Responsibilities

Description : 1. Block level and top level Digital Design implementation from RTL to Physical Design, including Synthesis, DFT, DV, floorplan, CTS, P&R, Performance/Power/Area Optimization, Timing Closure, EM/IR and PV fixes, design signoff
2. design and sign-off methodology development and EDA flow enhancement
3. R&D, innovation and path-finding for most advanced process challenges
4. Quality infrastructure development and project/program management
5. A Self-motivated, strong ownership and commitment, quick learner, and good teamwork

Requirements

1.Familiar with process fabrication, CAD, algorithm, EDA tool, APR, timing, IR/EM, low power, physical verification, device modeling , A VLSI chip implementation or 3DIC
2. Innovative and good problem solving skills
3 Willing to learn all aspects of chip design and come up with new solutions
4. Familiar with AI/ML technology is a plus
5. Familiar with Script languages (shell, python, perl, TCL)

	Department	BT	BS	MT	Double	Major	dual	dualB	dualC	Mdes	MBA	Phd	MSc	MSR
Eligibilty :	AE	N	-	N	N		N	N	N	-	-	N	-	N
	BSBE	N	-	N	N		N	N	N	-	-	N	-	N
	CE	N	-	N	N		N	N	N	-	-	N	-	N
	CHE	N	-	N	N		N	N	N	-	-	N	-	N
	CSE	N	-	Y	N		Y	Y	Y	-	-	N	-	Y
	EE	N	-	Y	N		Y	Y	Y	-	-	N	-	Y
	ES	-	N	N	-		N	-	N	-	-	N	-	-
	ME	N	-	N	N		N	N	N	-	-	N	-	N
	MSE	N	-	Y	N		Y	Y	Y	-	-	N	-	Y
	PHY	-	N	-	N		N	N	N	-	-	N	N	-
	CHM	-	N	-	N		N	N	N	-	-	N	N	-
	MTH	-	N	-	N		Y	Y	Y	-	-	N	Y	-
	ECO	-	N	-	N		N	N	N	-	-	N	-	-
	DES	-	-	-	-		-	-	N	N	-	N	-	-
	IME	-	-	N	-		-	N	N	-	N	N	-	-
	CGS	-	-	-	-		-	-	-	-	-	N	-	N
	HSS	-	-	-	-		-	-	-	-	-	N	-	-
	EEM	-	-	N	-		-	N	-	-	-	N	-	-
	MSP	-	-	Y	-		-	-	-	-	-	N	-	-
	NET	-	-	N	-		-	N	-	-	-	N	-	-
	PSE	-	-	Y	-		-	Y	-	-	-	N	-	Y
	Stats	-	-	-	-		-	-	-	-	-	N	Y	-

Cost to Company :	Item (Annual)	Master Degree
	GROSS	\$A A A A A A A A A A A A A A 49,813
	CTC	\$A A A A A A A A A A A A A A 58,913

Currency: USD

Package Details : 1. Including 12 months base pay, 2 months Year-end bonus, 18 months Profit Sharing, Design Incentive Bonus, 2 months relocation bonus, 4-6 months sign on bonus.
2. Base Salary, Year-end bonus, Design Incentive Bonus are fixed and recurring. Profit Sharing A is minimum amount for an average performance (i.e. top 50%) and recurring. Relocation and sign on bonus are one shot paid after onboard.

Bond :

True

Bond Details :

24 months

Medical Requirements :

Resume Shortlist :

True

Resume Shortlist Criteria:

N/A

Aptitude Test:

False

Group Discussion:

False

Technical Test:

False

Technical Interview:

True

Technical Interview Duration:

60 mins

Number of Techincal Interview Rounds:

1

HR Interview:

True

HR Interview Duration:

60 mins
